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Waste electrical and electronic equipment (WEEE) handbook

Edited by Vannessa Goodship and Ab Stevels



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Waste electrical and electronic equipment (WEEE) handbook

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Contents

Contributor contact details Woodhead Publishing Series in Electronic and Optical Materials Preface		xv xxi xxv
Part I	Legislation and initiatives to manage WEEE	1
1	Global e-waste initiatives R. KUEHR, United Nations University	3
1.1	Introduction	3
1.2	Problems associated with e-waste	4
1.3	Global e-waste management initiatives	6
1.4	Synergizing e-waste initiatives	13
1.5	Future trends	14
1.6	Sources of further information and advice	15
1.7	References	15
2	EU legislation relating to electronic waste: the WEEE and RoHS directives and the REACH regulations R. STEWART, Consultant, UK	17
2.1	Introduction	17
2.2	The EU and the environment	21
2.3	The Waste Framework Directive	25
2.4	The WEEE Directive	26
2.5	The WEEE Directive in operation	32
2.6	The recast of the WEEE Directive	33
2.7	Directive on the restriction of the use of certain hazardous	
	substances in electrical and electronic equipment (RoHS)	38
2.8	The Commission's proposal on a recast RoHS	41
2.9	Registration, Evaluation, Authorisation and restriction of	
	CHemicals (REACH) Directive	44

2.10 2.11 2.12	Review of REACH Summary References	48 49 49
3	The present recast of the WEEE Directive A. L. N. Stevels, Delft University of Technology, The Netherlands	53
3.1 3.2	Introduction Review studies proposing options for the recast of the WEEE Directive	53
2.2	The summer means of for the recent of WEEE	55
5.5 2.4	Further developments (July, Sentember 2011)	02
5.4 2.5	Conclusions	04 65
5.5 2.6	Deferences	05
3.0	Kelerences	03
4	The WEEE Forum and the WEEELABEX project P. LEROY, WEEE Forum aisbl, Belgium	66
4.1	Introduction	66
4.2	What is the WEEE Forum?	67
4.3	Context of WEEELABEX	68
4.4	WEEELABEX phase I: standards	73
4.5	WEEELABEX phase II: conformity verification	76
4.6	Conclusions	77
4.7	References	77
5	Conformity assessment of WEFE take-back	
0	schemes: the case of Switzerland H. W. Böni, Empa, Switzerland	78
5.1	Introduction	78
5.2	Approach of the conformity assessment	81
5.3	Scope and elements of the conformity assessment	82
5.4	Future trends	88
5.5	Conclusions	90
5.6	References	91
6	Eco-efficiency evaluation of WEEE take-back	
	SYSTEMS J. HUISMAN, Delft University of Technology, The Netherlands and United Nations University	93
6.1	Introduction	93
6.2	How much WEEE is out there?	94
6.3	How do WEEE quantify and prioritise environmental	
	impacts?	105

vi

Contents

	Contents	vii
6.4 6.5	How much do WEEE have to pay? How do WEEE benefit from impact assessment in policy	110
6.6	development? Conclusions	114 117
6.7	Kelerences	118
Part II	Technologies for refurbishment, treatment and recycling of waste electronics	121
7	The materials of WEEE M. GOOSEY, Loughborough University, UK	123
7.1	The material content of WEEE	123
7.2 7.3	Materials and their recovery and recycling technologies The transition from cathode ray tube (CRT) to liquid crystal display (LCD) screens and its implications for	126
	materials recycling	129
7.4	The loss of scarce elements	132
7.5	Novel materials recovery approaches	133
7.6	New materials and their implications	137
7.7	Summary and conclusions	140
7.8	Sources of further information and advice	140
7.9	References	142
8	Refurbishment and reuse of WEEE W. L. IJOMAH, University of Strathclyde, UK, and M. DANIS, Fujitsu Technology Solutions, UK	145
0.1		1.4.5
8.1 8.2	Reuse processes and their role in sustainable	145
	manufacturing	146
8.3	Industry sector specific example: refurbishment of	
	computers	150
8.4	Role of the third sector	152
8.5	Issues in WEEE refurbishment and reuse	153
8.6	Future trends	157
8.7	Summary of WEEE reuse and refurbishment	160
8.8	References	161
9	Shredding, sorting and recovery of metals from WEEE: linking design to resource efficiency A. VAN SCHAIK, MARAS – Material Recycling and Sustainability, The Netherlands, and M. A. REUTER, Outotec Oyj, Finland	163
9.1	Introduction	163

	<u> </u>
VIII	Contents

9.2	Theory of recycling	169
9.3	Product design, shredding and liberation of waste products	176
9.4	Automated and manual sorting of WEEE products	182
9.5	Metallurgical processing	188
9.6	(Dynamic) modelling recycling systems performance	198
9.7	Conclusions	207
9.8	References	210
10	Mechanical methods of recycling plastics from WEEE K. MAKENJI and M. SAVAGE, University of Warwick, UK	212
10.1	Introduction	212
10.2	Introduction to waste collection and sorting	216
10.3	Methods of sorting small particle size polymer waste	223
10.4	Conversion of WEEE to a reusable material	228
10.5	Effectiveness of the WEEE legislation to date	231
10.6	Remanufacturing using WEEE polymers	233
10.7	Future trends	234
10.8	Sources of further information and advice	235
10.9	References	235
11	Pyrolysis of WEEE plastics M. P. Luda, University of Turin, Italy	239
11.1	Introduction	239
11.2	Pyrolysis processes and characterization of the pyrolysis	
	fractions	240
11.3	Pyrolysis of printed circuit boards (PCBs)	248
11.4	Pyrolysis of plastics	249
11.5	Environmental concerns about the products of pyrolysis of	
	WEEE	253
11.6	Future trends	257
11.7	References	260
12	Chemical or feedstock recycling of WEEE products A. TUKKER, TNO, The Netherlands and Norwegian University of Science and Technology, Norway	264
12.1	Introduction	264
12.2	Characteristics of WEEE plastics	266
12.3	European feedstock recycling initiatives since the 1990s	267
12.4	Conclusions and future trends	281
12.5	References	282

Part III	Electronic products that present particular challenges for recyclers	285
13	Recycling printed circuit boards J. LI and X. ZENG, Tsinghua University, China	287
13.1	Introduction	287
13.2	Materials	291
13.3	Flame retardants	294
13.4	Costs and benefits of recycling printed circuit boards	
	(PCBs)	298
13.5	Challenges and future trends	306
13.6	References	310
14	Recycling liquid crystal displays K. S. WILLIAMS and T. McDONNELL, University of Central Lancashire, UK	312
14.1	Introduction	312
14.2	Liquid crystal displays (LCDs)	313
14.3	Recycling processes for liquid crystal displays (LCDs)	319
14.4	Hazardous materials in liquid crystal displays (LCDs)	326
14.5	Recovery of valuable materials	330
14.6	Re-use of liquid crystal display (LCD) equipment and	
	components	331
14.7	Future trends	332
14.8	Sources of further information and advice	333
14.9	References	334
15	Recycling cooling and freezing appliances C. KERI, Reclay Österreich GmbH, Austria	339
15.1	Introduction	339
15.2	Challenges relating to WEEE refrigerators and freezers	342
15.3	Requirements for de-gassing processes	343
15.4	Emissions of volatile organic compounds (VOCs)	344
15.5	Future trends	346
15.6	Techniques for separation of fridge plastics	348
15.7	Sources of further information and advice	350
15.8	Conclusions	350
15.9	References	351
16	End-of-life options for printed electronics M. KESKINEN, Tampere University of Technology, Finland	352
16.1	Introduction	352